IN THE CLAIMS:

1. (Currently amended) An integrated circuit device comprising:

a heat spreader comprising a top surface and a bottom surface;

at least one integrated circuit die attached to the top surface of the heat spreader; and

a flexible leadframe attached to the top surface of ~~a~~ the heat spreader and comprising one or more flexible layers including at least one flexible insulating layer, ~~and~~ a plurality of electrically conductive traces defined on the at least one flexible insulating layer, and at least one embedded circuit component, wherein the one or more flexible layers are configured for use as a flexible leadframe in ~~an~~ the integrated circuit device.

2. (Original) The integrated circuit device of claim 1, wherein two or more flexible layers are stacked together.

3. (Original) The integrated circuit device of claim 1, wherein the flexible leadframe and the top surface of the heat spreader define an interior area configured for receiving the at least one integrated circuit die, and wherein the integrated circuit die is electrically connected to the flexible leadframe.

4. (Original) The integrated circuit device of claim 1, further comprising a lid attached to the flexible leadframe, wherein the lid encloses an interior area configured for receiving the at least one integrated circuit die.

5. (Original) The integrated circuit device of claim 4, wherein the lid comprises at least one of metal, plastic, polyimide, plastic with metal coating, and ceramic.

6. (Canceled)

7. (Currently amended) The integrated circuit device of claim ~~6~~ 1, wherein the at least one embedded circuit component comprises one or more signal filters.

8. (Currently amended) The integrated circuit device of claim ~~6~~ 1, wherein the at least one embedded circuit component comprises one or more tuning capacitors

9. (Currently amended) The integrated circuit device of claim ~~6~~ 1, wherein the at least one embedded circuit component comprises one or more inductors.

10. (Currently amended) A flexible leadframe comprising:

one or more flexible layers comprising at least one flexible insulating layer; ~~and~~

a plurality of electrically conductive traces defined on the at least one flexible insulating layer; and

at least one embedded circuit component;

wherein the one or more flexible layers are configured for use as a flexible leadframe in an integrated circuit device.

11. (Original) The flexible leadframe of claim 10, wherein two or more flexible layers are laminated together.

12. (Original) The flexible leadframe of claim 10, wherein the one or more flexible layers comprise at least one polyimide layer.

13-22. (Canceled)